



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: **Howard R. Test, et al.**

Docket No.: **TI-30589**

Serial No.: **09/817,696**

Examiner: **Richards, N.D.**

Filed: **03/23/2001**

Art Unit: **2815**

For: **Wire Bonding Process for Copper-Metallized  
Integrated Circuits**

Conf. No.: **9348**

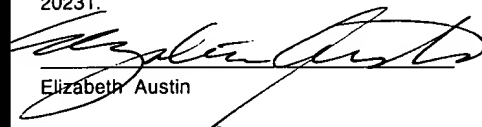
**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner For Patents  
Washington, DC 20231

Dear Sir:

**MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.

 **3/31/2003**  
Elizabeth Austin Date

Applicant wishes to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449. Copies of the listed references are enclosed.

Please charge any fee necessary to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

04/10/2003 SSURLES 00000002 200668 09817696  
01 FC:1806 180.00 CH

Respectfully submitted,



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